

# PXTA42

300 V, 100 mA NPN high-voltage transistor

Rev. 5 — 11 July 2011

Product data sheet

## 1. Product profile

### 1.1 General description

NPN high-voltage transistor in a medium power and flat lead SOT89 (SC-62) Surface-Mounted Device (SMD) plastic package.

PNP complement: PXTA92.

### 1.2 Features and benefits

- High breakdown voltage
- AEC-Q101 qualified
- Medium power and flat lead SMD plastic package

### 1.3 Applications

- Electronic ballast for fluorescent lighting
- LED driver for LED chain module
- High Intensity Discharge (HID) front lighting
- Automotive motor management
- Hook switch for wired telecom
- Switch Mode Power Supply (SMPS)

### 1.4 Quick reference data

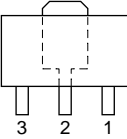
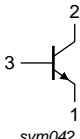
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CE0}$	collector-emitter voltage	open base	-	-	300	V
$I_C$	collector current		-	-	100	mA
$I_{CM}$	peak collector current		-	-	200	mA
$h_{FE}$	DC current gain	$V_{CE} = 10\text{ V};$ $I_C = 30\text{ mA}$	40	-	-	



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	emitter		 sym042
2	collector		
3	base		

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PXTA42	SC-62	plastic surface-mounted package; exposed die pad for good heat transfer; 3 leads	SOT89

## 4. Marking

Table 4. Marking codes

Type number	Marking code <sup>[1]</sup>
PXTA42	*1D

[1] \* = placeholder for manufacturing site code

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	300	V
$V_{CEO}$	collector-emitter voltage	open base	-	300	V
$V_{EBO}$	emitter-base voltage	open collector	-	6	V
$I_C$	collector current		-	100	mA
$I_{CM}$	peak collector current		-	200	mA
$I_{BM}$	peak base current		-	100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	1300	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	96	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	16	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

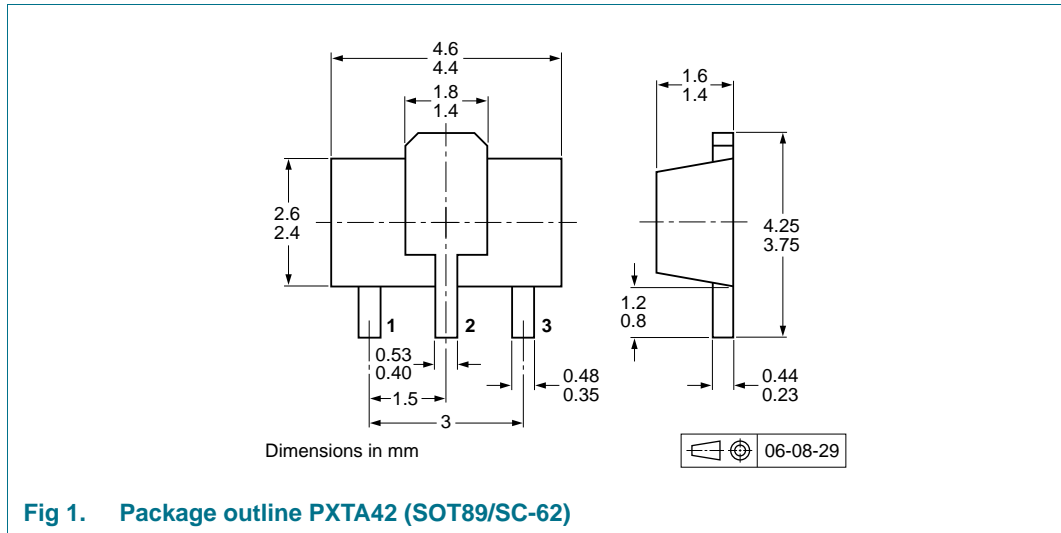
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 200\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 6\text{ V}; I_C = 0\text{ A}$	-	-	100	nA
$h_{FE}$	DC current gain	$V_{CE} = 10\text{ V}; I_C = 1\text{ mA}$	25	-	-	
		$V_{CE} = 10\text{ V}; I_C = 10\text{ mA}$	40	-	-	
		$V_{CE} = 10\text{ V}; I_C = 30\text{ mA}$	40	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 20\text{ mA}; I_B = 2\text{ mA}$	-	-	500	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 20\text{ mA}; I_B = 2\text{ mA}$	-	-	900	mV
$f_T$	transition frequency	$V_{CE} = 20\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	50	-	-	MHz
$C_{re}$	feedback capacitance	$V_{CB} = 20\text{ V}; I_C = I_E = 0\text{ A}; f = 1\text{ MHz}$	-	-	3	pF

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



## 10. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			1000	4000
PXTA42	SOT89	8 mm pitch, 12 mm tape and reel; T1	<sup>[2]</sup> -115	-135
		8 mm pitch, 12 mm tape and reel; T3	<sup>[3]</sup> -120	-

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T3: 90° taping

11. Soldering

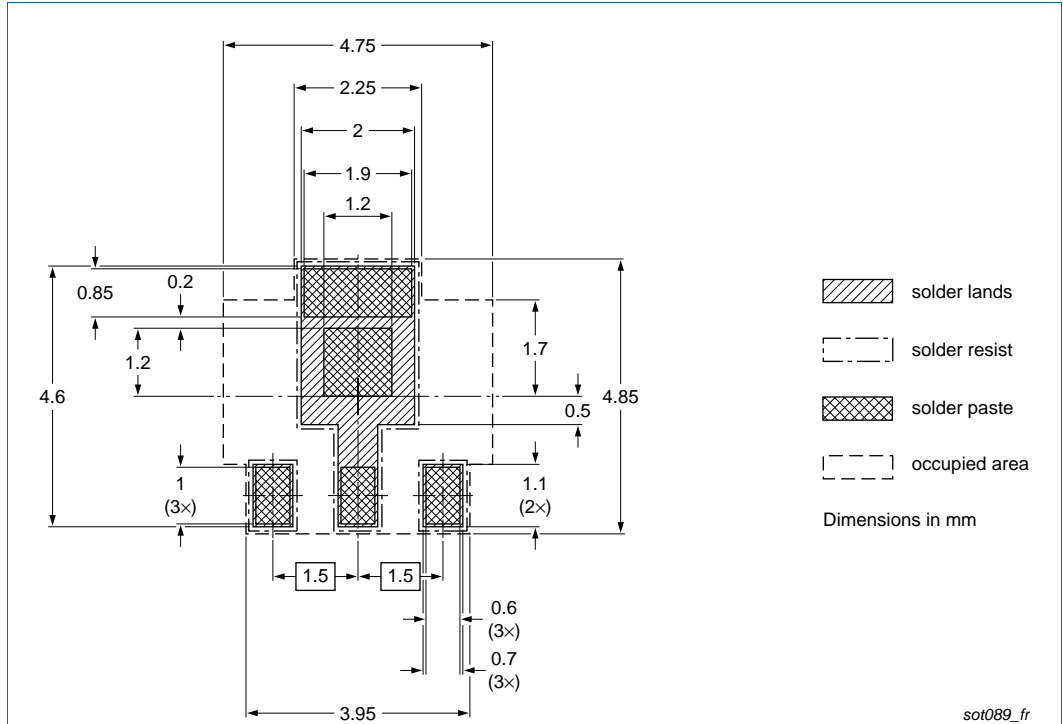


Fig 2. Reflow soldering footprint PXTA42 (SOT89/SC-62)

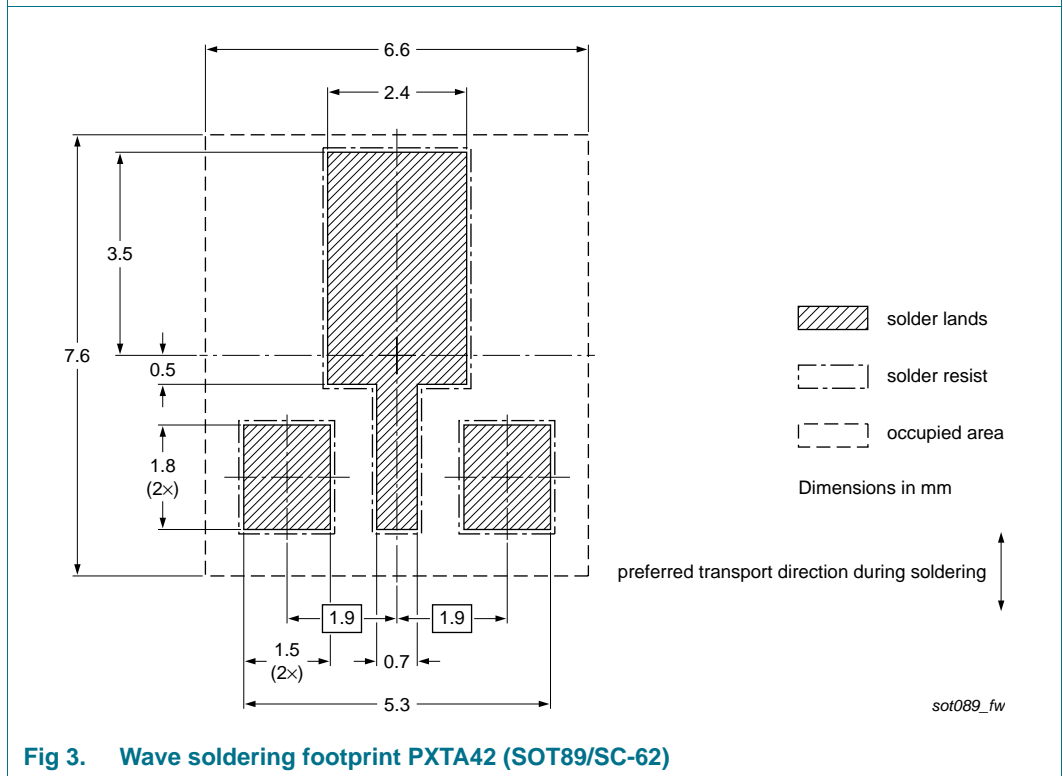


Fig 3. Wave soldering footprint PXTA42 (SOT89/SC-62)

## 12. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PXTA42 v.5	20110711	Product data sheet	-	PXTA42 v.4
Modifications:	<ul style="list-style-type: none"> <li>• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Section 1.1 “General description”</a>: amended</li> <li>• <a href="#">Section 1.2 “Features and benefits”</a>: amended</li> <li>• <a href="#">Section 1.3 “Applications”</a>: amended</li> <li>• <a href="#">Section 1.4 “Quick reference data”</a>: added</li> <li>• <a href="#">Figure 1</a>: superseded by minimized package outline drawing</li> <li>• <a href="#">Section 8 “Test information”</a>: added</li> <li>• <a href="#">Section 10 “Packing information”</a>: added</li> <li>• <a href="#">Section 11 “Soldering”</a>: added</li> <li>• <a href="#">Section 13 “Legal information”</a>: updated</li> </ul>			
PXTA42 v.4	20041209	Product data sheet	-	PXTA42 v.3
PXTA42 v.3	19990426	Product specification	-	PXTA42_43_CNV v.2
PXTA42_43_CNV v.2	19970618	Product specification	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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